

## **INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION #16790HD**

Generic Copy

#### Issue Date: 27-Aug-2014

**<u>TITLE</u>**: Initial PCN wafer fab transfer from Gunma and Gifu in Japan to Niigata in Japan.

**PROPOSED FIRST SHIP DATE:** starting 27-Dec-2014 until 22-Apr-2015 (the actual ship date will be different by each product, please check the responsible Sales person).

AFFECTED CHANGE CATEGORY(S): Wafer Fabrication Location Change

#### FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor Sales Office or < Yasuhiro.Igarashi@onsemi.com>

#### NOTIFICATION TYPE:

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 97 days prior to implementation of the change.

#### **DESCRIPTION AND PURPOSE:**

This is an Initial Process Change Notification to announce about the transfer of products from ON Semiconductor wafer fabrication sites located in Gifu Japan to the wafer fabrication ON Semiconductor Niigata Co., Ltd.(OSNC). OSNC is located in Niigata, Japan, obtained ISO9001 certification.

The product design and electrical specifications will remain identical. A full electrical characterization over the temperature range will be performed for each product to check the device functionality and electrical specifications. Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards.

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#### **QUALIFICATION PLAN:**

Reliability Test was planned as below. Reliability Test Results will be provided in the FPCN.

Test Items	Test Condition	Test Time	
High Temperature Storage	Tstg max	1000	h
Temperature Humidity Storage	Ta=85°C,RH=85%	1000	h
Steady State Operating Life	Tch,Tjmax	1000	h
High Temperature Revers Bias	Tstg rmax,(VDSSmax,VCESmax,VRmax)	1000	h
Temperature Cycle	Ta=Tstg min to max,30min each	200	Cycle
Pressure Cooker (Autoclave)	Ta=121degC,RH=100%,2.03×10 <sup>6</sup> Pa	50	h
Soldering Test	260degC,10s(Soldering bath)	1	time

# Reliability Test Plan

Notice)

#### List of affected General parts:

2SJ652-1E	CPH3355-TL-H	MCH3383-TL-H	SCH1333-TL-H
2SJ661-1E	CPH3356-TL-H	MCH3479-TL-H	SCH1335-TL-H
2SJ661-DL-1E	CPH3456-TL-H	MCH3481-TL-H	SCH1337-TL-H
2SJ665-1E	CPH6355-TL-H	MCH3484-TL-H	SCH1433-S-TL-H
2SJ665-DL-1E	CPH6443-P-TL-H	MCH6331-TL-H	SCH1433-TL-H
2SK3703-1E	CPH6443-TL-H	MCH6344-TL-H	SCH1439-TL-H
2SK3707-1E	FW216A-TL-2W	MCH6431-P-TL-H	SFT1350-H
2SK3816-DL-1E	FW217A-TL-2W	MCH6431-TL-H	SFT1350-TL-H
2SK3820-DL-1E	FW344A-TL-2W	MCH6437-P-TL-E	SFT1431-TL-E
2SK4065-DL-1E	FW4604-TL-2W	MCH6437-TL-E	SFT1450-H
BXL4004-1E	MCH3382-TL-H	SCH1332-TL-H	SFT1450-TL-H